

ABSTRACT OF THE DISCLOSURE

An apparatus for inspecting a wafer includes a handling unit for supporting, rotating and moving the wafer in horizontal and vertical directions, a first image acquisition unit for acquiring a first image corresponding to an upper surface of the wafer supported by the handling unit, a second image acquisition unit for acquiring a second image, a third image and a fourth image corresponding to a peripheral portion of the upper surface, a side surface and a lower surface of the wafer supported by the handling unit, respectively, a first driving unit for rotating the second image acquisition unit about a peripheral portion of the wafer supported by the handling unit in order to acquiring the second, third and fourth images, and an image processing unit for inspecting defects of the wafer supported by the handling unit from the first to fourth images.